

Claims

1. A method for providing a PCB (printed circuit board) with a shield can (1;11;21;31) comprising a metal shell with a free rim (5;15;25;35), said method comprising the steps of:
- providing the PCB (12) with solder (16),
 - placing the shield can (1;11;21;31) on the PCB (12) with the rim (5;15;25;35) towards the PCB (12),
 - heating the PCB (12) and the shield can (1;11;21;31) to a temperature above a melting temperature of the solder (16),
 - cooling the PCB (12) and the shield can (1;11;21;31),
- characterised in** that the rim (5;15;25;35) of the shield can (1;11;21;31) is provided with an extra amount of solder (8;18) before the shield can (1;11;21;31) is placed on the PCB (12).
2. A method according to claim 1, **characterised in** that the rim (5;15;25;35) of the shield can (1) is provided with the extra amount of solder (8) by dipping it partly into a bath of molten solder (8).
3. A method according to claim 1, **characterised in** that recesses (19;29) are provided at the rim (15;25) of the shield can (11;21) before the extra amount of solder (18) is applied thereto; and that the extra amount of solder (18) is applied to the recesses.
4. A method according to claim 1 or 3, **characterised in** that the rim (5;15;25) of the shield can (1;11;21) is provided with the extra amount of solder (8;18) by a screen-printing process.
5. A method according to claim 1 or 2, **characterised in** that indentations (39) are provided at the rim of the shield can (31) before the extra amount of solder is applied thereto; and that the extra amount of solder is applied to the indentations (39).
6. A shield can (1;11;21;31) for electro-magnetically shielding an electronic component mounted on a printed circuit board (PCB), said shield can (1;11;21;31) comprising a metal shell with a free rim (5;15;25;35),

characterised in that the rim (5;15;25;35) of the shield can (1;11;21;31) is provided with an extra amount of solder (8;18).

5 7. A shield can according to claim 6, **characterised in** that the rim (15;25) of the shield can (11;21) is provided with a plurality of recesses (19;29), each recess (19;29) being provided with an extra amount of solder (18).

8. A shield can according to claim 7, **characterised in** that each recess (19;29) is V-shaped.

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9. A shield can according to claim 6, **characterised in** that the rim (35) of the shield can (31) is provided with a plurality of indentations (39), each indentation (39) being provided with an extra amount of solder.

15 10. A shield can according to claim 9, **characterised in** that each indentation (39) is V-shaped.

11. A shield can according to any one of claims 6-10, **characterised in** that the shield can (1;11;21;31) is box-shaped with a flat upper shell part (3;13) and four downwardly extending side pieces (4;14;24;34) with the free rim (5;15;25;35).

12. A shield can according to claim 11, **characterised in** that the side pieces (14;24;34) are interconnected at adjoining corners; and that each corner is provided with a leg (20) that protrudes downwards beyond the free rim (15;25;35).

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